

## DIFFERENTIAL BUS TRANSCEIVER

### FEATURES

- **One-Fourth Unit Load Allows up to 128 Devices on a Bus**
- **ESD Protection for Bus Terminals:**
  - $\pm 15$ -kV Human Body Model
  - $\pm 8$ -kV IEC61000-4-2, Contact Discharge
  - $\pm 15$ -kV IEC61000-4-2, Air-Gap Discharge
- **Meets or Exceeds the Requirements of ANSI Standard TIA/EIA-485-A and ISO 8482: 1987(E)**
- **Controlled Driver Output-Voltage Slew Rates Allow Longer Cable Stub Lengths**
- **Designed for Signaling Rates† Up to 250-kbps**
- **Low Disabled Supply Current . . . 250  $\mu$ A Max**
- **Thermal Shutdown Protection**
- **Open-Circuit Fail-Safe Receiver Design**
- **Receiver Input Hysteresis . . . 70 mV Typ**
- **Glitch-Free Power-Up and Power-Down Protection**

### DESCRIPTION

The SN65LBC182 and SN75LBC182 are differential data line transceivers with a high level of ESD protection in the trade-standard footprint of the SN75176. They are designed for balanced transmission lines and meet ANSI standard TIA/EIA-485-A and ISO 8482. The SN65LBC182 and SN75LBC182 combine a 3-state, differential line driver and differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can be externally connected together to function as a direction control.

The driver outputs and the receiver inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus.

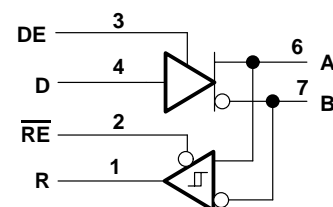
This port operates over a wide range of common-mode voltage, making the device suitable for party-line applications. The device also includes additional features for party-line data buses in electrically noisy environment applications such as industrial process control or power inverters.

The SN75LBC182 and SN65LBC182 bus pins also exhibit a high input resistance equivalent to one-fourth unit load allowing connection of up to 128 similar devices on the bus. The high ESD tolerance protects the device for cabled connections. (For an even higher level of protection, see the SN65/75LBC184, literature number SLLS236.)

The differential driver design incorporates slew-rate-controlled outputs sufficient to transmit data up to 250 kbps. Slew-rate control allows longer unterminated cable runs and longer stub lengths from the main backbone than possible with uncontrolled voltage transitions. The receiver design provides a fail-safe output of a high level when the inputs are left floating (open circuit). Very low device supply current can be achieved by disabling the driver and the receiver.

The SN65LBC182 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ , and the SN75LBC182 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

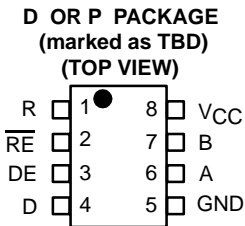
### functional block diagram



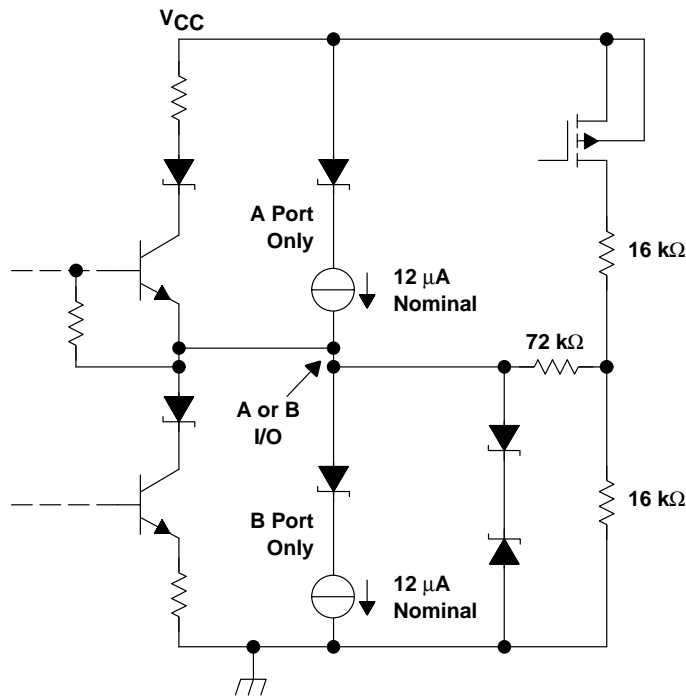
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†The signaling rate of a line, is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



schematic of inputs and outputs



Function Tables

DRIVER

INPUT D	ENABLE DE	OUTPUTS	
		A	B
H	H	H	L
L	H	L	H
X	L	Z	Z
Open	H	H	L

RECEIVER

DIFFERENTIAL INPUTS	ENABLE RE	OUTPUT R
$V_{ID} \geq 0.2\text{ V}$	L	H
$-0.2\text{ V} < V_{ID} < 0.2\text{ V}$	L	?
$V_{ID} \leq -0.2\text{ V}$	L	L
X	H	Z
Open	L	H

AVAILABLE OPTIONS

T <sub>A</sub>	PACKAGE	
	PLASTIC SMALL-OUTLINE† (JEDEC MS-012)	PLASTIC DUAL-IN-LINE PACKAGE (JEDEC MS-001)
0°C to 70°C	SN75LBC182D	SN75LBC182P
–40°C to 85°C	SN65LBC182D	SN65LBC182P

† Add R suffix for taped and reel.

## absolute maximum ratings†

Supply voltage range, (see Note 1) $V_{CC}$	–0.5 V to 7 V
Voltage range at any bus terminal (A or B)	–15 V to 15 V
Input voltage, $V_I$ (D, DE, R or $\overline{RE}$ )	–0.3 V to 7 V
Electrostatic discharge: Human body model (see Note 2)	A, B, GND 15 kV
	All pins 3 kV
Contact discharge (IEC61000-4-2)	A, B, GND 8 kV
Air discharge (IEC61000-4-2)	A, B, GND 15 kV
Continuous total power dissipation	See Dissipation Rating Table
Storage temperature range, $T_{stg}$	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.  
2. Tested in accordance with JEDEC Standard 22, Test Method A114-A.

**DISSIPATION RATING TABLE**

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR‡ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW
P	1150 mW	9.2 mW/°C	736 mW	598 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

NOTE: The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature

## recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.75	5	5.25	V
Voltage at any bus I/O terminal (separately or common mode) V <sub>I</sub> or V <sub>IC</sub>		−7		12	V
High-level input voltage, V <sub>IH</sub>	D, DE, $\overline{RE}$	2		0.8	V
Low-level input voltage, V <sub>IL</sub>					
Differential input voltage, V <sub>ID</sub> (see Note 3)		−12		12	V
Output current, I <sub>O</sub>	Driver	−60		60	mA
	Receiver	−8		4	
Operating free-air temperature, T <sub>A</sub>	SN65LBC182	−40		85	°C
	SN75LBC182	0		70	

NOTE 3: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

**driver electrical characteristics over recommended operating conditions**

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>IK</sub>	Input clamp voltage	I <sub>I</sub> = -18 mA	-1.5			V
V <sub>O</sub>	Output voltage	I <sub>O</sub> = 0	0		V <sub>CC</sub>	V
V <sub>OD</sub>	Differential output voltage	R <sub>L</sub> = 54 Ω, See Figure 1	1.5	2.2	V <sub>CC</sub>	V
		V <sub>test</sub> = -7 V to 12 V, See Figure 2	1.5	2.2	V <sub>CC</sub>	V
ΔV <sub>OD</sub>	Change in magnitude of differential output voltage	See Figure 1	-0.2		0.2	V
V <sub>OC(SS)</sub>	Steady-state common-mode output voltage		1		3	
ΔV <sub>OC(SS)</sub>	Change in steady-state common-mode output voltage	See Figures 1 and 4	-0.2		0.2	V
V <sub>OC(PP)</sub>	Peak-to-peak change in common-mode output voltage during state transitions			0.8		
I <sub>OZ</sub>	High-impedance output current	See receiver input currents				
I <sub>IH</sub>	High-level input current (D, DE)	V <sub>I</sub> = 2.4 V			50	μA
I <sub>IL</sub>	Low-level input current (D, DE)	V <sub>I</sub> = 0.4 V	-50			μA
I <sub>OS</sub>	Short-circuit output current	V <sub>O</sub> = -7 V to 12 V	-250		250	mA
I <sub>CC</sub>	Supply current	SN75LBC182		12	25	mA
		SN65LBC182		12	30	

† All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

**driver switching characteristics over recommended operating conditions (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>r</sub>	Differential output signal rise time	R <sub>L</sub> = 54 Ω, C <sub>L</sub> = 50 pF, See Figure 3	0.25	0.72	1.2	μs
t <sub>f</sub>	Differential output signal fall time		0.25	0.73	1.2	
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output				1.3	
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output				1.3	
t <sub>sk(p)</sub>	Pulse skew (t <sub>PHL</sub> - t <sub>PLH</sub> )			0.075	0.15	
t <sub>PZH</sub>	Output enable time to high level	R <sub>L</sub> = 110 Ω, See Figure 5			3.5	μs
t <sub>PHZ</sub>	Output disable time from high level				3.5	
t <sub>PZL</sub>	Output enable time to low level	R <sub>L</sub> = 110 Ω, See Figure 6			3.5	μs
t <sub>PLZ</sub>	Output disable time from low level				3.5	

**receiver electrical characteristics over recommended operating conditions (unless otherwise noted)**

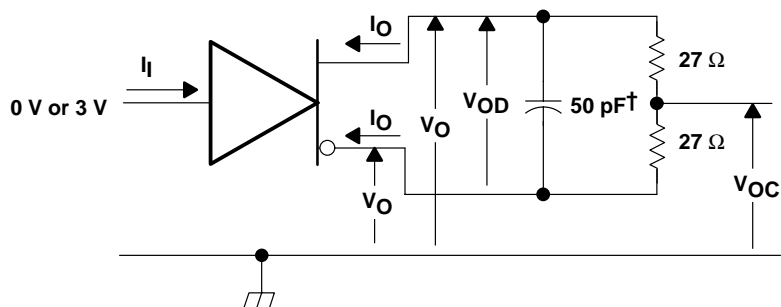
PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{IT+}$ Positive-going input threshold voltage			0.2		V
$V_{IT-}$ Negative-going input threshold voltage		-0.2			
$V_{hys}$ Hysteresis voltage ( $V_{IT+} - V_{IT-}$ )			70		mV
$V_{IK}$ Enable-input clamp voltage	$I_I = -18$ mA	-1.5			V
$V_{OH}$ High-level output voltage	$V_{ID} = 200$ mV, $I_O = -8$ mA, See Figure 7	2.8			V
$V_{OL}$ Low-level output voltage	$V_{ID} = 200$ mV, $I_O = 4$ mA, See Figure 7		0.4		V
$I_{OZ}$ High-impedance-state output current	$V_O = 0.4$ to $2.4$ V		$\pm 1$		$\mu$ A
$I_I$ Bus input current	$V_{IH} = 12$ V, $V_{CC} = 5$ V	Other input at 0 V	250		$\mu$ A
	$V_{IH} = 12$ V, $V_{CC} = 0$ V		250		
	$V_{IH} = -7$ V, $V_{CC} = 5$ V		-200		
	$V_{IH} = -7$ V, $V_{CC} = 0$ V		-200		
$I_{IH}$ High-level input current ( $\overline{RE}$ )	$V_{IH} = 2$ V		50		$\mu$ A
$I_{IL}$ Low-level input current ( $\overline{RE}$ )	$V_{IL} = 0.8$ V		-50		$\mu$ A
$I_{CC}$ Supply current	No load	DE at 0 V, $\overline{RE}$ at 0 V		3.5	mA
		DE at 0 V, $\overline{RE}$ at $V_{CC}$	175	250	$\mu$ A

† All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^\circ\text{C}$ .

**receiver switching characteristics over recommended operating conditions (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_r$ Differential output signal rise time	$C_L = 50$ pF, See Figure 7		20		ns
$t_f$ Differential output signal fall time			20		
$t_{PLH}$ Propagation delay time, low-to-high-level output				150	
$t_{PHL}$ Propagation delay time, high-to-low-level output				150	
$t_{PZH}$ Output enable time to high level	See Figure 8			100	ns
$t_{PZL}$ Output enable time to low level				100	
$t_{PHZ}$ Output disable time from high level				100	ns
$t_{PLZ}$ Output disable time from low level				100	
$t_{sk(p)}$ Pulse skew $ t_{PHL} - t_{PLH} $				50	ns

## PARAMETER MEASUREMENT INFORMATION



†Includes probe and jig capacitance

Figure 1. Driver Test Circuit,  $V_{OD}$  and  $V_{OC}$  Without Common-Mode Loading

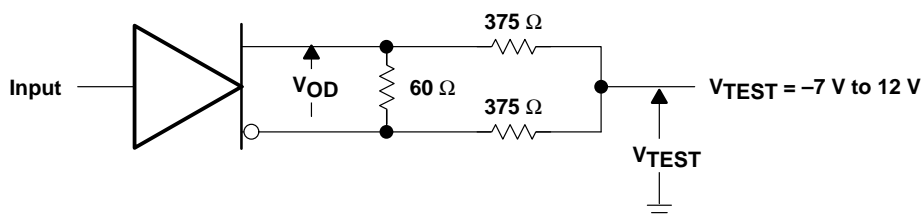
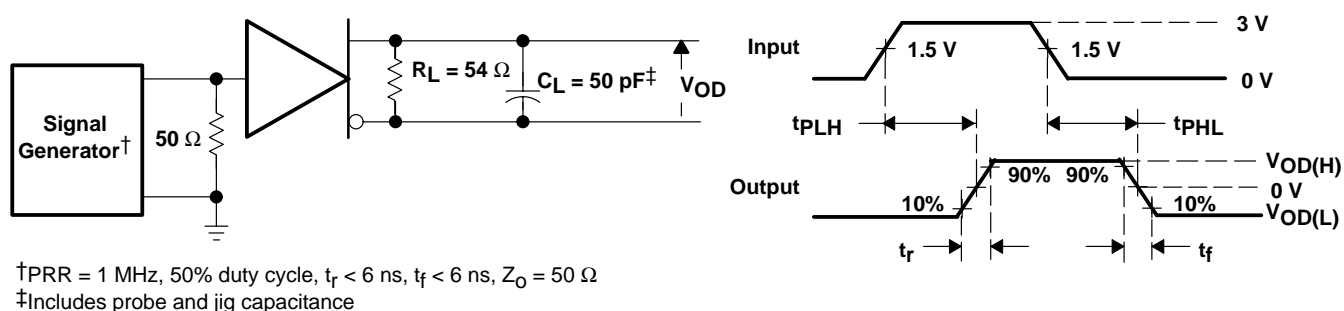


Figure 2. Driver Test Circuit,  $V_{OD}$  With Common-Mode Loading



†PRR = 1 MHz, 50% duty cycle,  $t_r < 6$  ns,  $t_f < 6$  ns,  $Z_O = 50 \Omega$

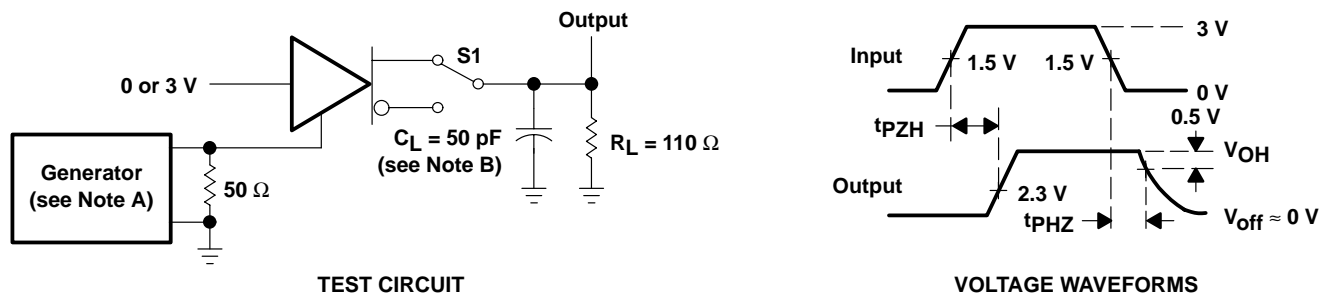
‡Includes probe and jig capacitance

Figure 3. Driver Switching Test Circuit and Waveforms



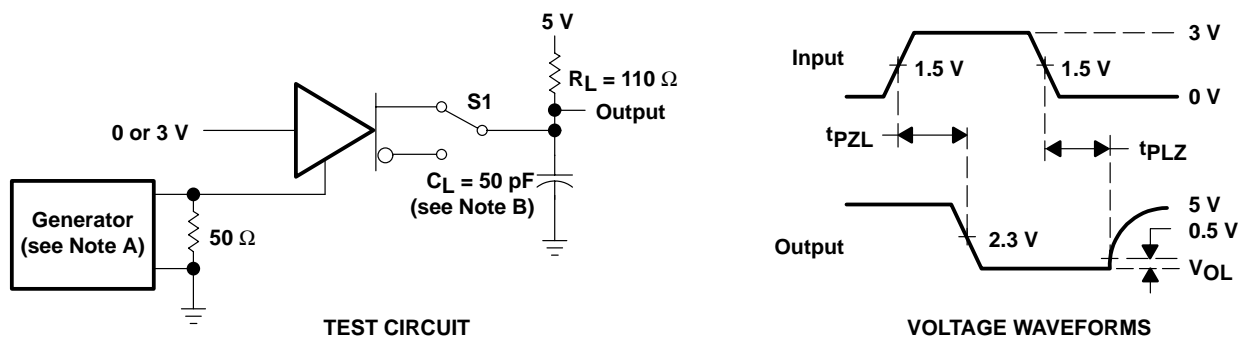
Figure 4.  $V_{OC}$  Definitions

## PARAMETER MEASUREMENT INFORMATION



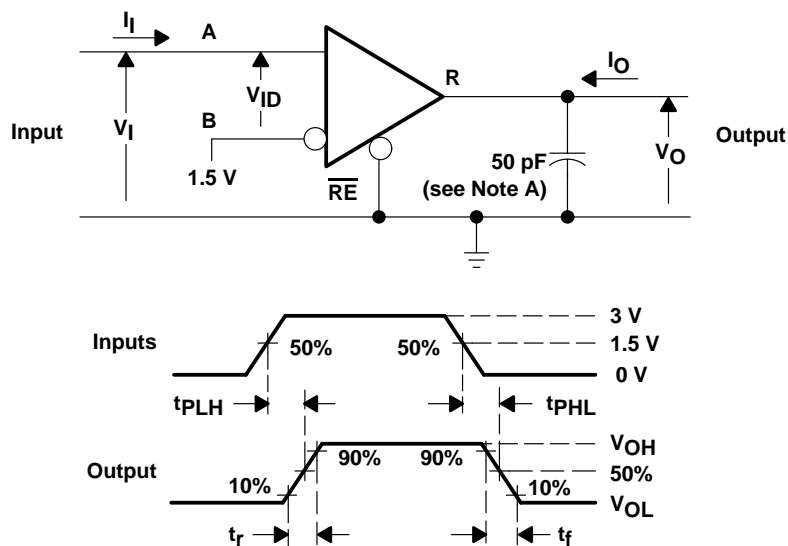
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1.25 kHz, 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns,  $Z_O = 50$   $\Omega$ .  
B.  $C_L$  includes probe and jig capacitance.

Figure 5. Driver  $t_{pZH}$  and  $t_{pHZ}$  Test Circuit and Voltage Waveforms



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1.25 kHz, 50% duty cycle,  $t_r \leq 10$  ns,  $t_f \leq 10$  ns,  $Z_O = 50$   $\Omega$ .  
B.  $C_L$  includes probe and jig capacitance.

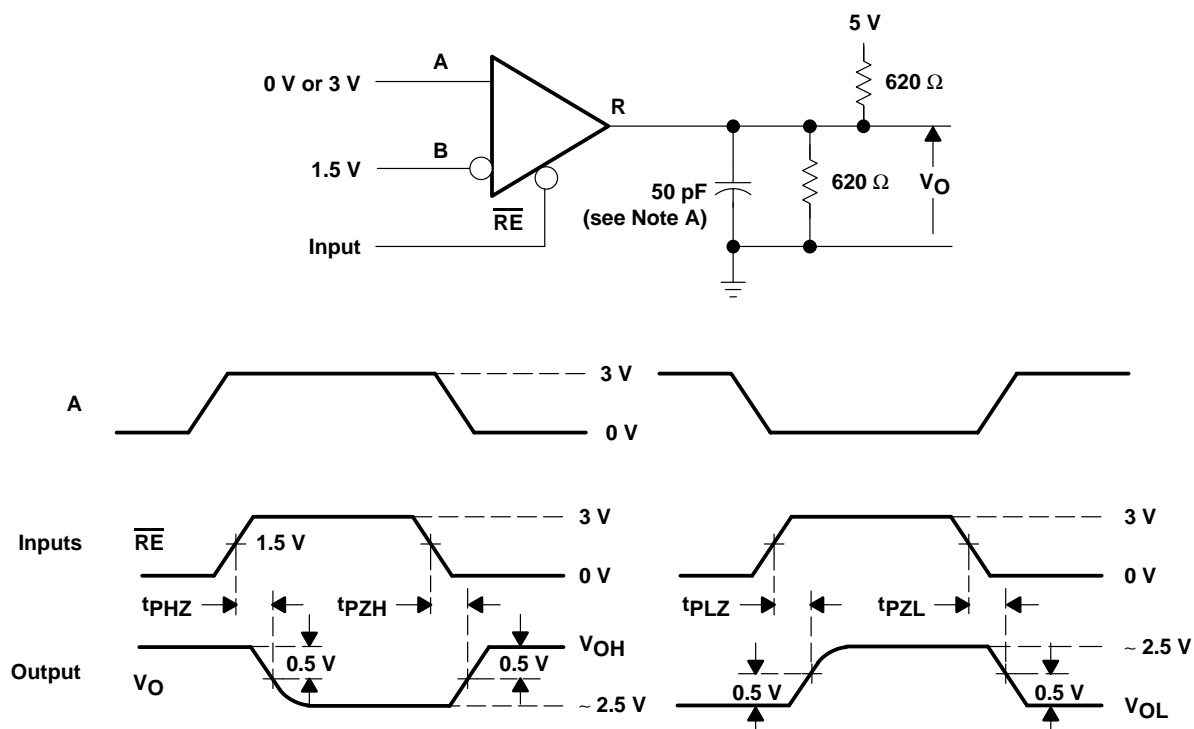
Figure 6. Driver  $t_{pZL}$  and  $t_{pLZ}$  Test Circuit and Voltage Waveforms



NOTE A: This value includes probe and jig capacitance ( $\pm 10\%$ ).

Figure 7. Receiver  $t_{pLH}$  and  $t_{pHL}$  Test Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION



NOTE A: This value includes probe and jig capacitance ( $\pm 10\%$ ).

Figure 8. Receiver  $t_{PZL}$ ,  $t_{PLZ}$ ,  $t_{PZH}$ , and  $t_{PHZ}$  Test Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

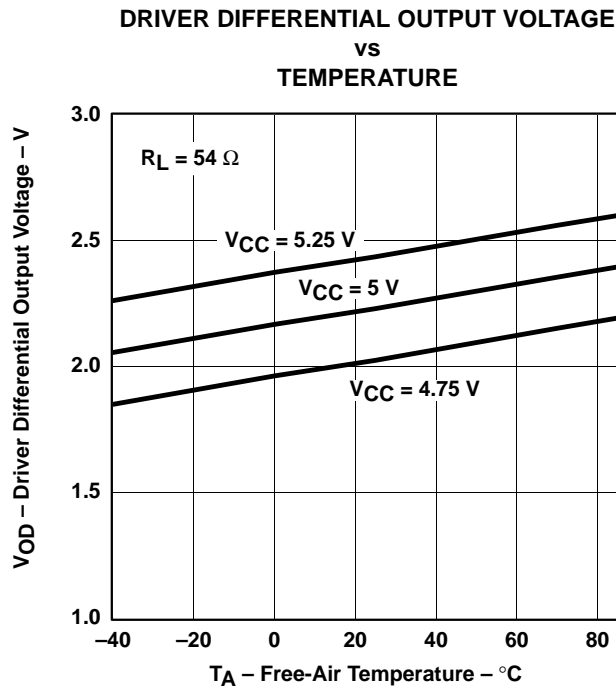


Figure 9

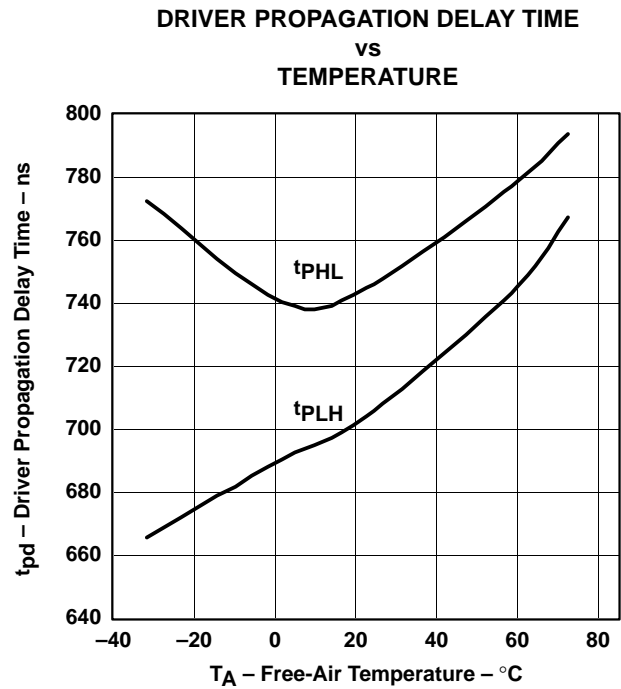


Figure 10

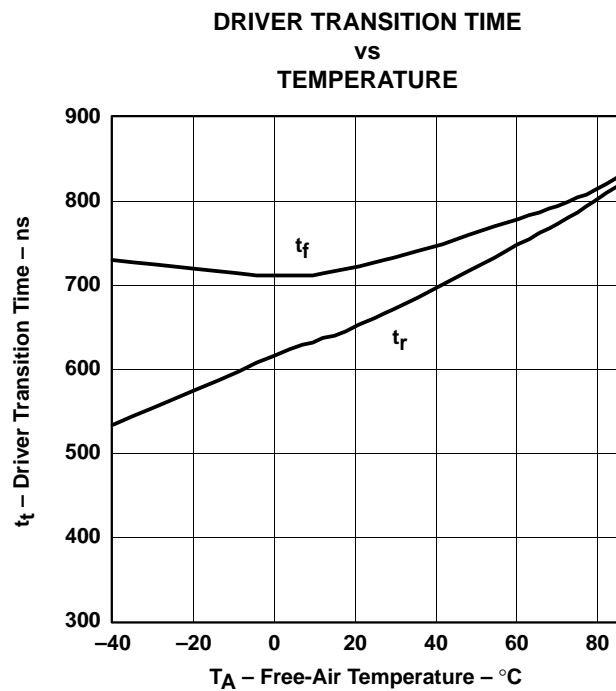


Figure 11

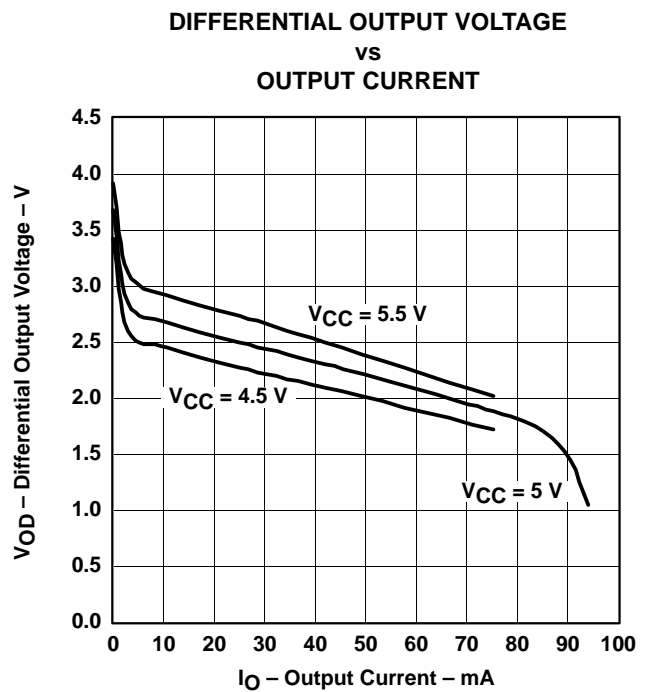


Figure 12

TYPICAL CHARACTERISTICS

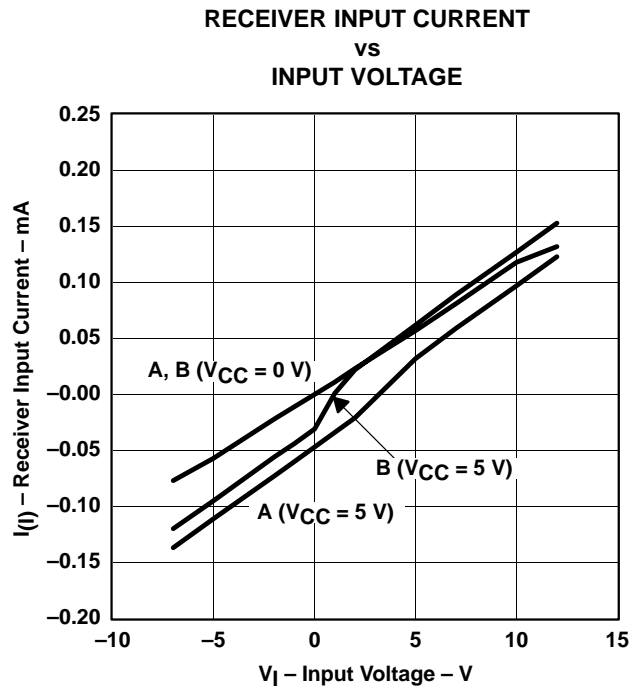
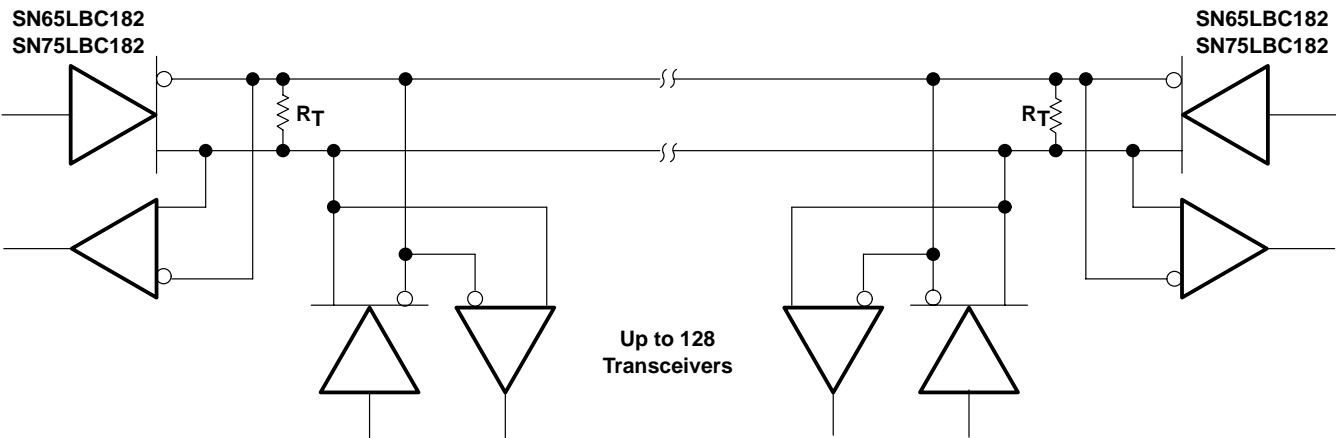


Figure 13

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance ( $R_T = Z_0$ ). Stub lengths off the main line should be kept as short as possible.

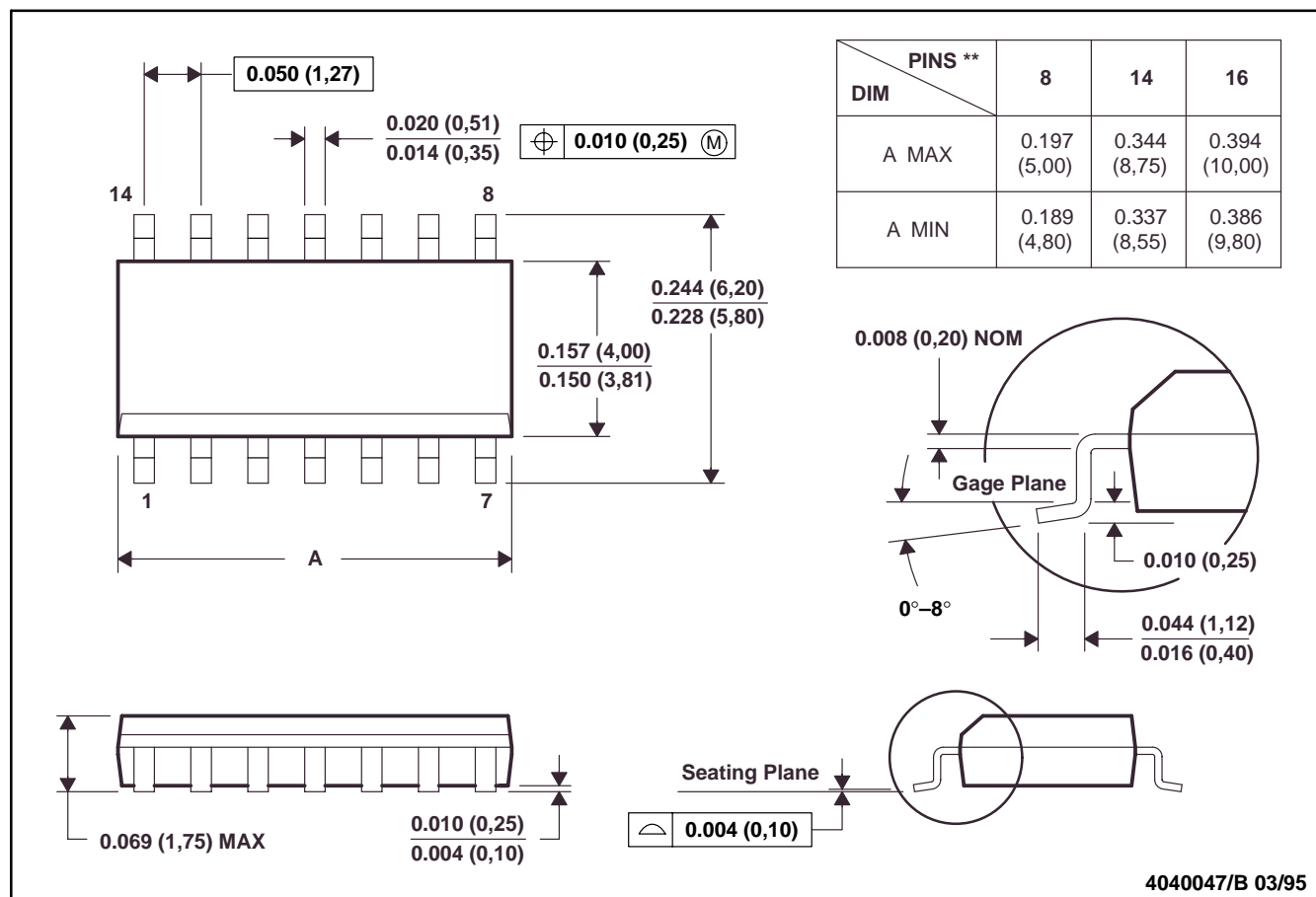
Figure 14. Typical Application Circuit

# MECHANICAL INFORMATION

D (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN

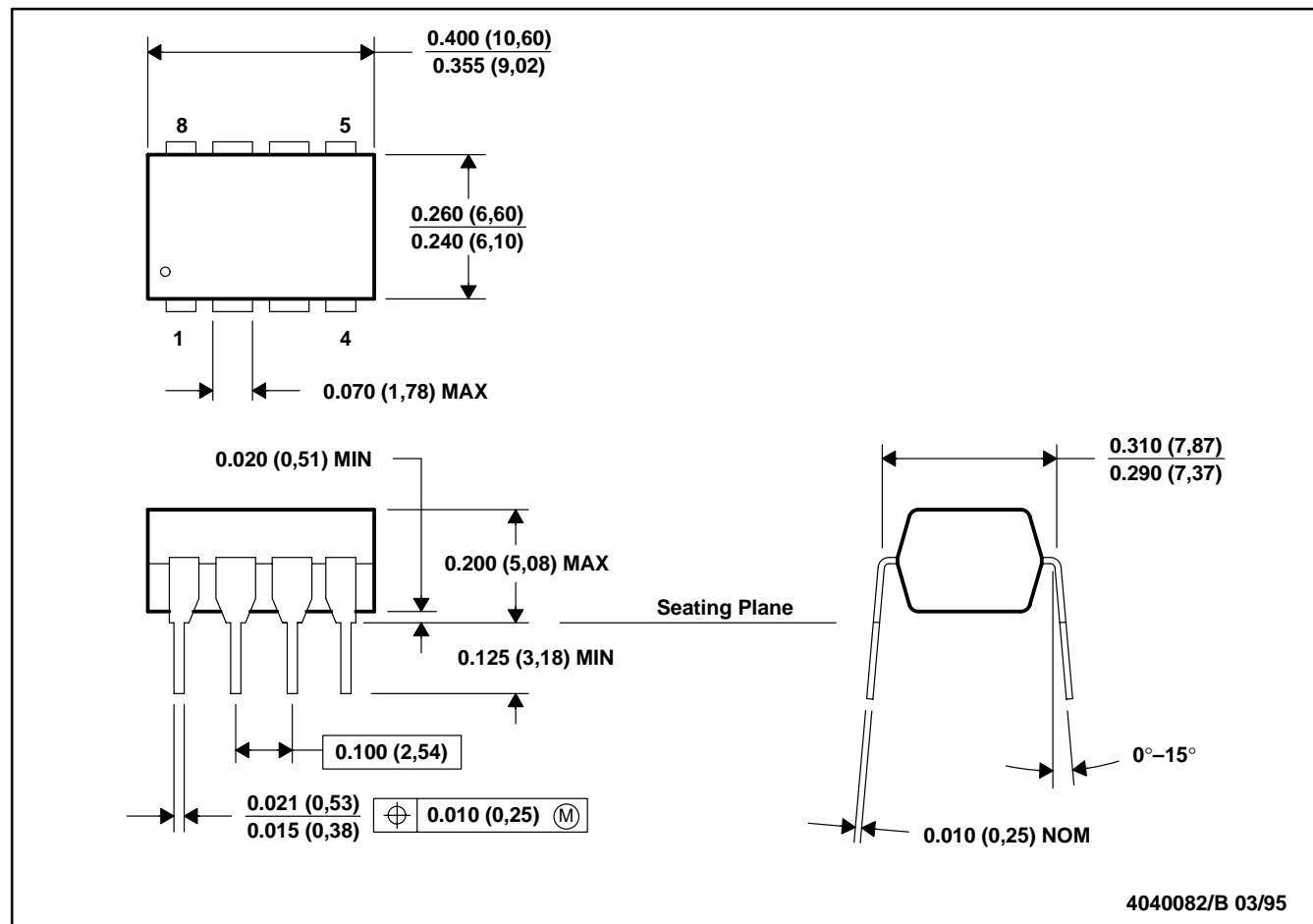


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
  - D. Four center pins are connected to die mount pad.
  - E. Falls within JEDEC MS-012

# MECHANICAL INFORMATION

**P (R-PDIP-T8)**

**PLASTIC DUAL-IN-LINE PACKAGE**



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MS-001

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